



Material Content Data Sheet



Sales Product Name		IFX30081SJV		Issued		4. March 2019			
MA#		MA005209778							
Package		PG-DSO-8-44		Weight*		82.65 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.989	1.20	1.20	11963	11963	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108		
		non noble metal	zinc	7440-66-6	0.036	0.04		434	
		non noble metal	iron	7439-89-6	0.717	0.87		8677	
wire	non noble metal	non noble metal	copper	7440-50-8	29.121	35.23	36.15	352336	361555
		non noble metal	copper	7440-50-8	0.041	0.05	0.05	500	500
		encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1208
encapsulation	plastics	epoxy resin	-	4.592	5.56		55553		
		inorganic material	silicondioxide	60676-86-0	45.217	54.70	60.38	547078	603839
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9847	9847	
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7867	7867	
glue	plastics	acrylic resin	-	0.081	0.10		974		
		noble metal	silver	7440-22-4	0.286	0.35	0.45	3455	4429
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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